Onsemi

FFSH40120ADN-F155

Description

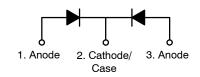
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

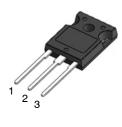
- Max Junction Temperature 175°C
- Avalanche Rated 200 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- This Device is Pb-Free, Halogen Free/BFR Free and RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

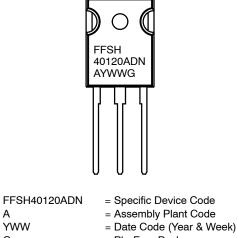


Schottky Diode



TO-247-3LD CASE 340CH

MARKING DIAGRAM



= Pb-Free Package

ORDERING INFORMATION

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See detailed ordering and shipping information on page 2 of this data sheet.

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Symbol	Parameter		Value	Unit
V _{RRM}	Peak Repetitive Reverse Voltage		1200	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		200	mJ
١ _F	Continuous Rectified Forward Current @ T _C < 148°C		20* / 40**	А
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	1190	А
		T _C = 150°C, 10 μs	990	А
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	135	А
I _{F,RM}	Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	74	А
P _{TOT}	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	220	W
		T _C = 150°C	37	W
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +175	°C
	TO-247 Mounting Torque, M3 Screw	60	Ncm	

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted) (per leg)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NOTE: * Per leg, ** Per Device.

1. E_{AS} of 200 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 29 A, V = 150 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max	0.68* / 0.34**	°C/W

NOTE: * Per leg, ** Per Device.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (per leg)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	$I_{F} = 20 \text{ A}, T_{C} = 25^{\circ}\text{C}$	-	1.45	1.75	V
		I _F = 20 A, T _C = 125°C	-	1.7	2.0	
		I _F = 20 A, T _C = 175°C	-	2.0	2.4	
I _R	Reverse Current	$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 25°C	-	-	200	μΑ
		$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 125°C	-	-	300	
		$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 175°C	-	-	400	
Q _C	Total Capacitive Charge	V = 800 V	-	120	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	1220	-	pF
		V _R = 400 V, f = 100 kHz	-	111	-	
		V _R = 800 V, f = 100 kHz	_	88	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

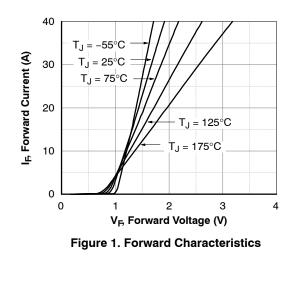
ORDERING INFORMATION

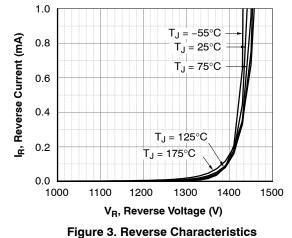
Part Number	Top Marking	Package	Packing Method	Quantity
FFSH40120ADN-F155	FFSH40120ADN	TO-247-3LD	Tube	30 Units

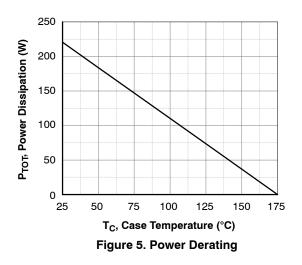
FFSH40120ADN-F155

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ UNLESS OTHERWISE NOTED (PER LEG)})$







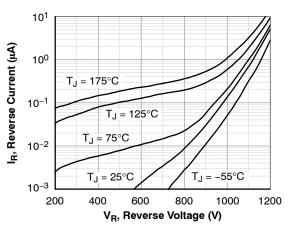
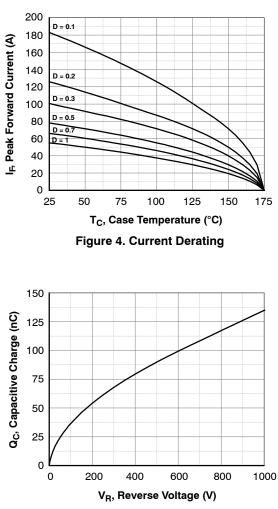


Figure 2. Reverse Characteristics





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 $\label{eq:typical characteristics} \begin{array}{l} \textbf{Typical characteristics} \ (\texttt{CONTINUED}) \\ \textbf{(} \textbf{T}_{\text{J}} = 25^{\circ}\texttt{C} \ \textbf{UNLESS} \ \textbf{OTHERWISE} \ \textbf{NOTED} \ \textbf{(PER LEG))} \end{array}$

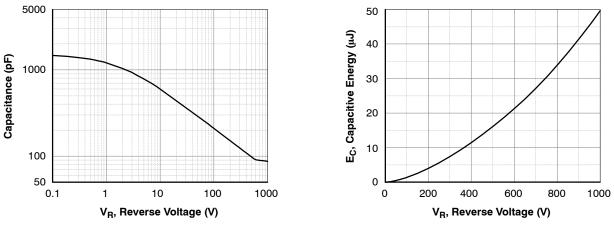
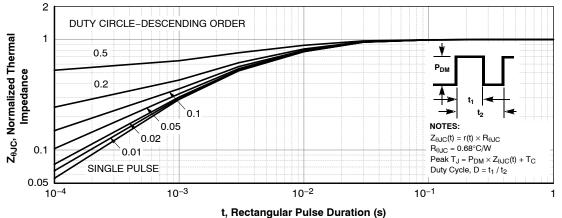


Figure 7. Capacitance vs. Reverse Voltage

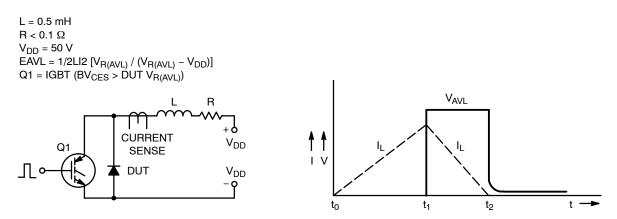


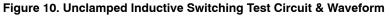


t, nectaligular Pulse Duration (s)

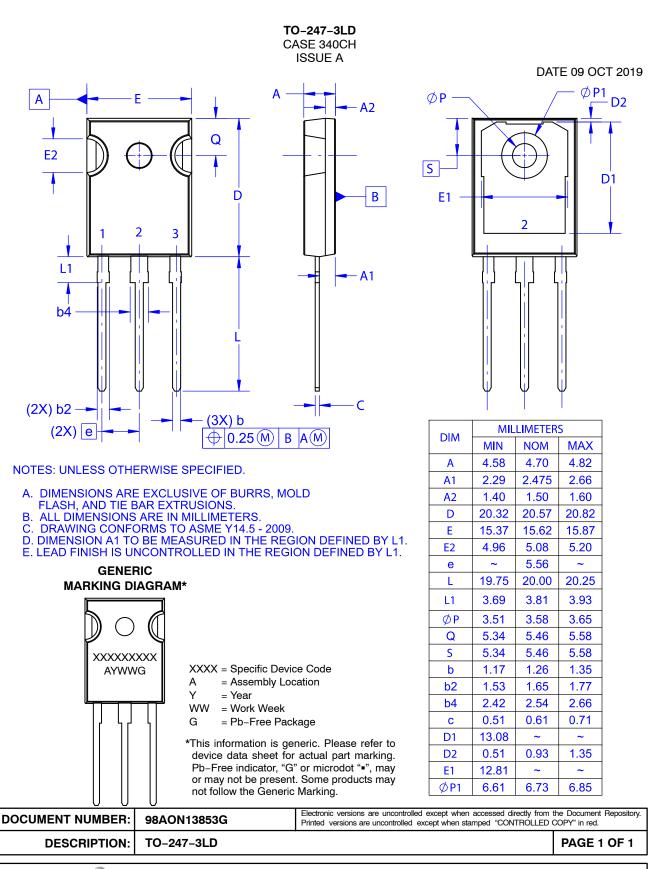
Figure 9. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS









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